SML-H12x Series

■Features
- Abundant color variations with diverse luminous intensity types.
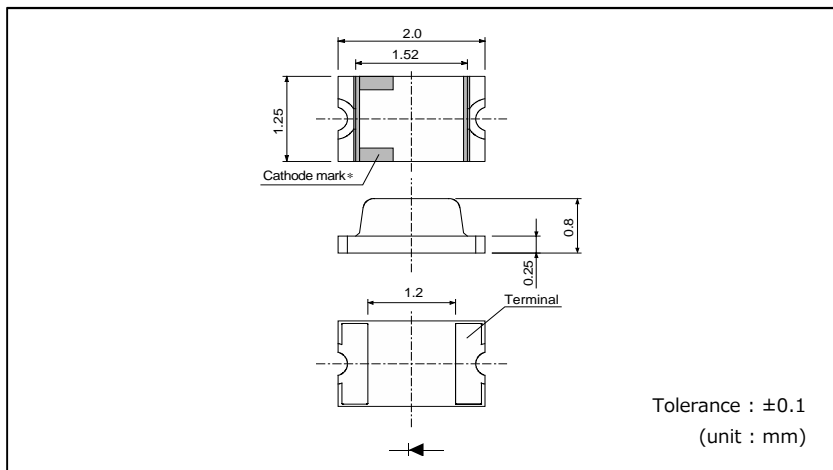
■Outline
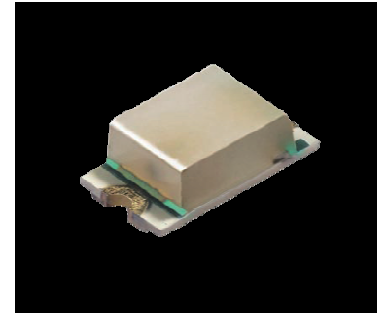
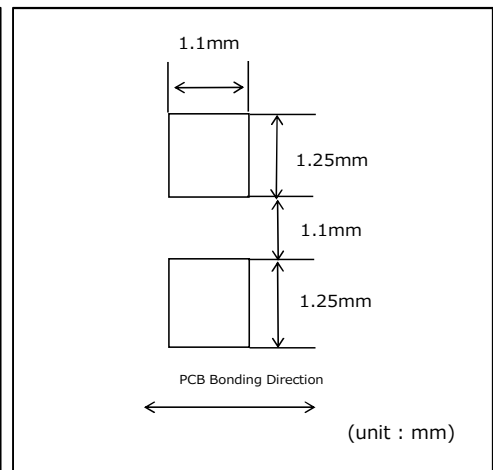## ■Size

2012（0805） 2.0×1.25mm（t=0.8mm）

Color Type

V	U	D
Y	M	P

■Dimensions

2.0
1.52
1.25
Cathode mark＊

0.8
0.25

1.2
Terminal

Tolerance : ±0.1
(unit : mm)

■Recommended Solder Pattern

1.1mm
1.25mm
1.1mm
1.25mm

PCB Bonding Direction

(unit : mm)

■Moisture sensitivity level(MSL) : Level 3

■Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25ºC)						Electrical and Optical Characteristics (Ta=25ºC)										
			Power Dissipation	Forward Current	Peak Forward Current	Reverse Voltage	Operating Temp.	Storage Temp.	Forward Voltage V$_F$		Reverse Current I$_R$		Dominant Wavelength λ_D				Luminous Intensity I$_V$		
									Typ.	I$_F$	Max.	V$_R$	Min.*2	Typ.	Max.*2	I$_F$	Min.	Typ.	I$_F$
			P$_D$(mW)	I$_F$(mA)	I$_{FP}$(mA)	V$_R$(V)	T$_{opr}$(ºC)	T$_{stg}$(ºC)	(V)	(mA)	(µA)	(V)	(nm)	(nm)	(nm)	(mA)	(mcd)	(mcd)	(mA)
■ SML-H12V8T	AlGaInP	Red	54	20	100*1	5	-40 ～ +85	-40 ～ +100	2.2	20	10	5	625	630	635	20	16	25	20
■ SML-H12U8T													615	620	625		25	40	
■ SML-H12D8T		Orange											602	605	608		40	63	
■ SML-H12Y8T		Yellow											587	590	593			63	
■ SML-H12M8T		Yellowish Green											569	572	575		10	25	
■ SML-H12P8T		Green											557	560	563		2.5	4	

*1 : Duty 1/10, 1KHz *2 : Measurement tolerance:±1nm

■ **Electrical Characteristics Curves**
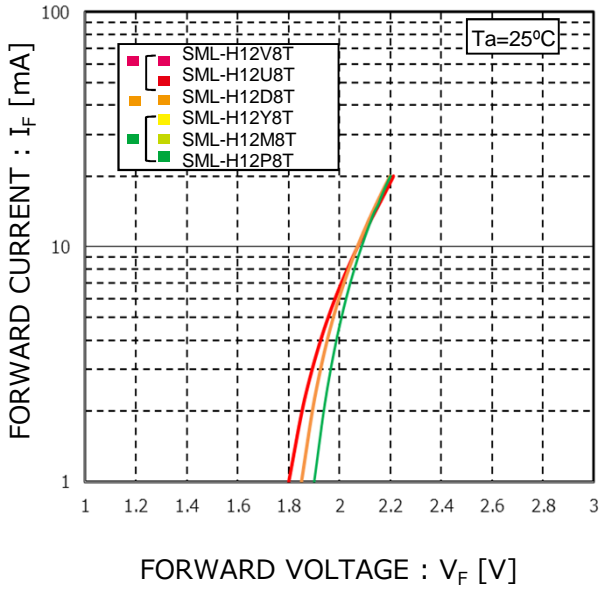
Fig.1 Forward Current
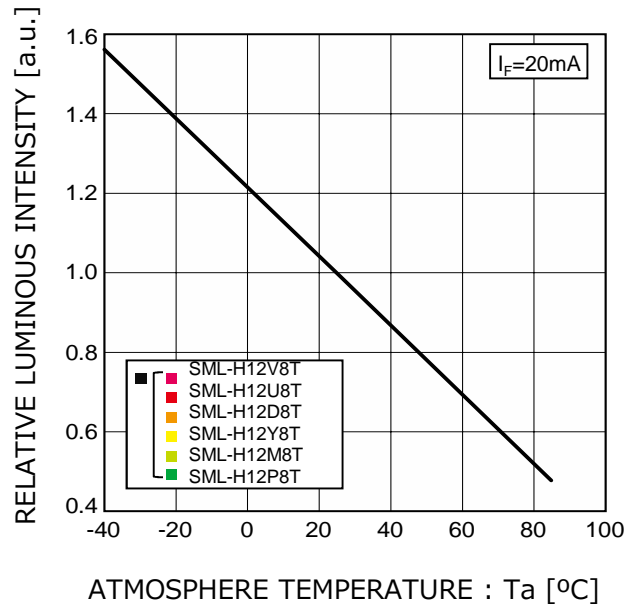- Forward Voltages

Fig.2 Luminous Intensity -
Atmosphere Temperature

Fig.3 Luminous Intensity - Forward Current

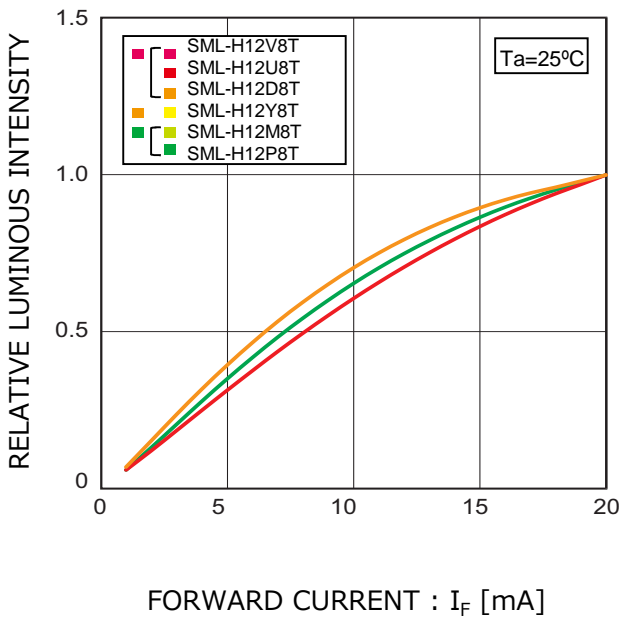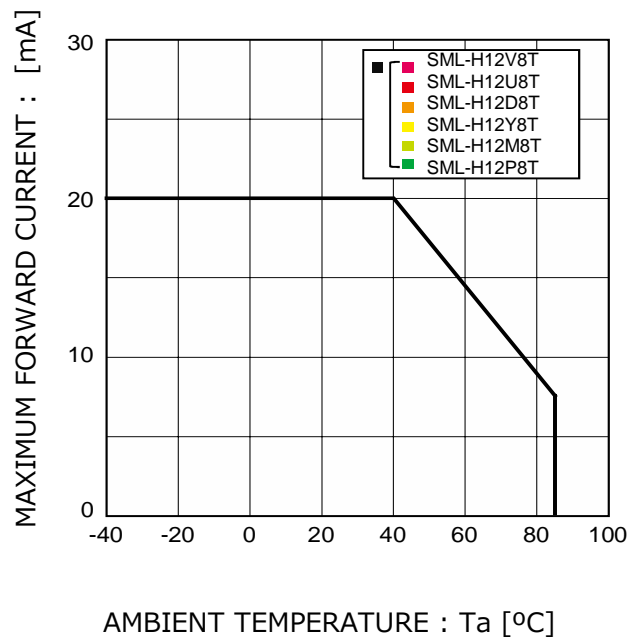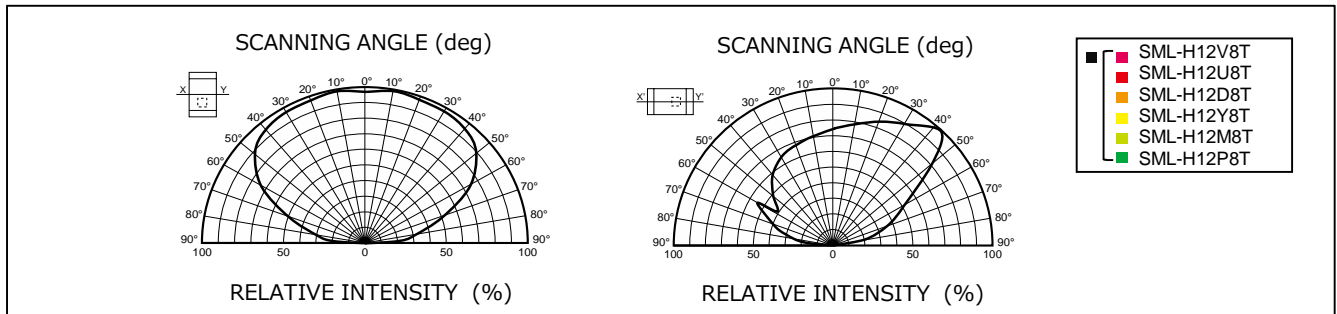Fig.4 Derating

■ Viewing Angle

■**Rank Reference of Brightness***   *Measurement tolerance:±10%

Red(V,U)
(Ta=25ºC, I$_F$=20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y	Z
Iv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500	2500~4000
SML-H12V8T							■	■	■									
SML-H12U8T								■	■	■								

Orange(D)
(Ta=25ºC, I$_F$=20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
Iv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12D8T									■	■	■						

Yellow(Y)
(Ta=25ºC, I$_F$=20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
Iv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12Y8T									■	■	■						

Yellowish Green/Green(M, P)
(Ta=25ºC, I$_F$=20mA)

Rank	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
Iv (mcd)	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12M8T							■	■	■									
SML-H12P8T				■	■	■												

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■Taping（T86）

Unit:mm

Packing quantity
3,000pcs/reel

Pull
direction

Note)Tolerance is within ±0.2mm unless
otherwise specified.

■Part No. Construction

*"-"will be taken out for emitting color
WB/B/E series.

Special Code will be applied for
Emitting color WB/B/E series.

Chromaticity rank
(for white LED)

Rank sign
(Brightness Rank)*

| S | M | L | – | H | 1 | 2 | Y | 8 | T | T | 8 | 6 | | P |

Series name

Package Type

Chip type

Emitting Color

Resin Color

Taping Specification

SML	Chip LED

P1	1.0x0.6 t=0.2mm
E1	1.6x0.8 t=0.36mm
D1	1.6x0.8 t=0.55mm
H1	2.0x1.25 t=0.8mm
M1	
01	3.0x2.0 t=1.3mm
Z1/ZN	3.5x2.8 t=1.9mm
A1	1.6x1.15 t=0.55mm
B1/B2	3.4x1.25 t=1.1mm
K1	4.5x2.0 t=0.6mm
S1	3.2x1.6 t=1.85mm
P2	1.0x1.0 t=0.2mm
52	1.3x1.5 t=0.6mm
P34	1.0x1.0 t=0.2mm
P36	1.5x1.0 t=0.2mm
VN	3.5x2.8 t=0.6mm

SCM	Chip LED

| 01 | 3.0x1.5 t=2.2mm |

0	Standard Type
1	Low Current Type
2	High Brightness type
3	
4	
5	Ultra High Brightness type
6	
7	
8	

V	Red
U	Red
U2	Red
D	Orange
Y3	Yellow
Y2	Yellow
Y	Yellow
W	Yellow
M2	Yellowish green
M	Yellowish green
F	Green
P	Green
E	Green
B	Blue
WB	White
T	Phototransistors
RGB	Red/Green/Blue

T	Transparent Colorless
W	Milky White
B	Black

| T86 | Cathode at sprocket hole side(the top) |

*Concerning the Brightness rank.
*Please refer to the rank chart above for
luminous intensity classification.
*Part name is individual for each rank.
*When shipped as sample,the part name will
be a representative part name.
General products are free of ranks.
Please contact sales if rank appointment
is needed.

■Packing Specification

Complying with IPC/JEDEC J-STD-033.

■Precaution (Surface Mount Device)

1．Storage

If the product is heated during the reflow under the condition of hygroscopic state,
it may vaporize and expand which will influence the performance of the product.
Therefore, the package is waterproof. Please use the product following the conditions:

・Using Conditions

Classification	Temperature	Humidity	Expiration Date	Remark
①Before using	5～30℃	30～70%RH	Within 1 year from Receiving	Storage with waterproof package
②After opening package	5～30℃	Below 70%RH	Within 168h	Please storing in the airtight container with our desiccant (silica gel)

・Baking
Bake the product in case of below:
①The expiration date is passed.
②The color of 5% and 10% on humidity indicator card is not green.
(Even if the product is before expiration date.)

・Baking Conditions

Temperature	Time	Humidity
60±3℃	12～24h	Below 20%RH
Remark	・Bake products in reel. ・Reel and embossed tape are easy to be deformed when baking, so please try not to apply stress on it. ・Recommend bake once.	

2．Application Methods

2－1．Precaution for Drive System and Off Mode
Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that
applies on the products. If drive by constant voltage, it may cause current deviation of the LED and
result in deviation of luminous intensity, so we recommend to drive by constant current.
 (Deviation of VF Value will cause deviation of current in LED.) Furthermore, for off mode,
please do not apply voltage neither forward nor reverse. Especially, for the products with the
Ag-paste used in the die bonding, there's high possibility to cause electro migration and result
in function failure.

2－2．About Derating
  It is considered that derating characteristics will not result in LED chip's electrical destruction.
Even within the derating, the reliability and luminous life can be affected depending on operating
conditions and ambient environment. So we would be appreciate it if you can confirm with your
application again.

2－3．About product life
Depending on operating conditions and environment(applied current, ambient temperature and
humidity, corrosive gas), decreasing of luminosity and change of chromaticity may occur even
within the specification conditions.
Please contact our sales office if you use it for the following applications.
①It requires long luminosity life
②It is always lit

2－4．Applied Stress on Product
No resin hardening agent such as filler is used in the sealing resin of the product.
Therefore, please pay attention to the overstress on it which may influence its reliability.

2－5．Usage
The Product is LED. We are not responsible for the usage as the diode such as Protection Chip,
Rectifier, Switching and so on.

3．Others

3－1．Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or
alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of
the plating surface) or optical characteristics changes (light intensity, chrominance) and change
in quality of cause die bonding (Ag-paste) materials. All of the above will function failure of
the products.
Therefore, please pay attention to the storage environment for mounted product (concern the
generated gas of the surrounding parts of the products and the atmospheric environment).

3－2．Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged
by the electrostatic discharge. Please take appropriate measures to avoid the static electricity from
human body and earthing of production equipment. Especially, InGaN type LEDs have lower resistance
value of electrostatic discharge and it is recommended to introduce the ESD protection circuit.
The resistance values of electrostatic discharge (actual values) vary with products, therefore,
please call our Sales staffs for inquiries.

3－3． Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED,
therefore please evaluate before using it.

4．Mounting

4－1．Soldering

・No resin hardening agent such as filler is used in the sealing resin of the product. Therefore, resin
 expansion and moisture absorption at humidity will cause heat stress during soldering process and
 finally has bad influence on the product's reliability.

・The product is not guaranteed for flow soldering.

・Do not expose the product in the environment of high temperature (over 100℃) or rapid temperature
 shift (within 3℃/sec. of temperature gradient) during the flow soldering of surrounding parts.
 In case of carrying out flow soldering of surrounding parts without recommended conditions, please
contact us for inquiries.

・Please set appropriate reflow temperature based on our product usage conditions and specification.

・The max for reflowing is 2 times, please finish the second reflow soldering and flow soldering
 with other parts within the usage limitation after open the moistureproof package.

・Compare with N2 reflow, during air reflow, because of the heat and surrounding conditions,
 it may cause the discoloration of the resin.

・For our product that has no solder resist, because of its solder amount and soldering conditions,
  one of its specific characteristics is that solder will penetrate into LED. Thus, there's high possibility
that will influence its reliability.Therefore, please be informed, concerning it before using it.

4－2．Automatic Mounting

4-2-1．Suction nozzle

Excessive load may cause damage inside the LED product, so select an optimal suction nozzle
according to the material and shape of the LED product.

4-2-2．Mini Package (Smaller than 1608 size)

・Vibration may result in low mounting rate since it will cause the static electricity of product and
 adhere to top cover tape. Therefore, the magnet should be set on parts feeder cassette of
 the mounter to control the product stabilization. In addition, it is recommended to set ionizer
 to prevent electrostatic charge.

4－3．Mounting Location

The stress like bending stress of circuit board dividing after mounting, may cause LED package crack
or damage of LED internal junction, therefore, please concern the mounting direction and position
 to avoid bending or screwing with great stress of the circuit board.
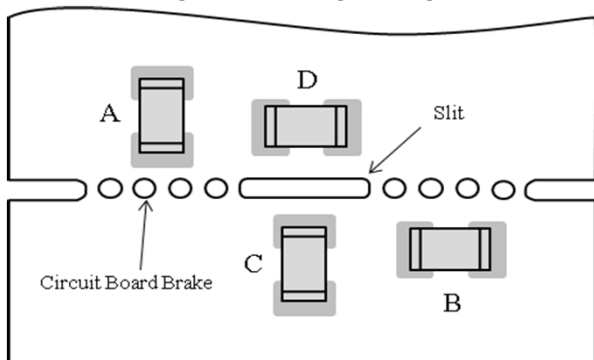
Stress strength according to
he mounting position:
A＞B＞C＞D

4－4．Mechanical Stress after Mounting

The mechanical stress may damage the LED after Circuit Mounting,
 so please pay attention to the touch on product.

4－5．Soldering Pattern for Recommendation

We recommend the soldering pattern that shows on the right.
It will be different according to mounting situation of circuit board,
therefore, please concern before designing.

1.1mm

1.25mm

1.1mm

1.25mm

PCB Bonding Direction
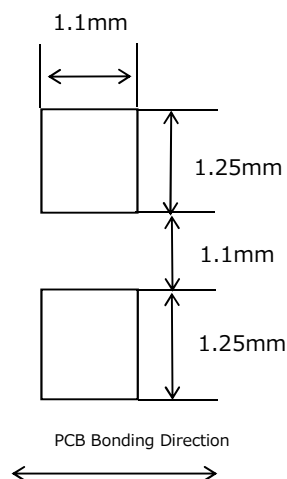
※The product has adopted the electrode structure that it should solder
   with back electrode of the product.
   Thus, please be informed that the shape of electrode pin of
   solder fillet formation is not guaranteed.
   The through hole on electrode surface is for conduction of front
   and rear electrodes but not for formation of solder fillet.

4 – 6 ．Reflow Profile

For reflow profile, please refer to the conditions below:(※)

■Meaning of marks, Conditions

Mark	Meanings	Conditions
Ts_{max}	Maximum of pre-heating temperature	180℃
Ts_{min}	Minimum of pre-heating temperature	140℃
t_s	Time from Tsmin to Tsmax	Over 60sec.
T_L	Reference temperature	230～260℃
t_L	Retention time for TL	Within 40sec.
T_P	Peak temperature	260℃(Max)
t_P	Time for peak temperature	Within 10sec.
$\Delta T_R/\Delta t$	Temperature rising rate	Under 3℃/sec.
$\Delta T_D/\Delta t$	Temperature decreasing rate	Over -3℃/sec.

※Above conditions are for reference. Therefore, evaluate by customer's own circuit boards and reflow furnaces before using, because stress from circuit boards and temperature variations of reflow furnaces vary by customer's own conditions.

4 – 7 ．Attention Points in Soldering Operation

This product was developed as a surface mount LED especially suitable for reflow soldering.
So reflow soldering is recommended. In case of implementing manual soldering,
please take care of following points.

①SOLDER USED

Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu

②HAND SOLDERING CONDITION

LED products do not contain reinforcement material such as a glass fillers.
So thermal stress by soldering greatly influence its reliability.
Please keep following points for manual soldering.

	ITEM	RECOMMENDED CONDITION
a)	Heating method	Condition) Temp. of iron top less than 400℃ within 3 sec. Heating on PCB pattern, not direct to the LED. (Fig-1)
b)	Handling after soldering	Please handle after the part temp. goes down to room temp.

Fig-1

SOLDERING IRON

SOLDERING LAND

4 – 8 ．Cleaning after Soldering

Please follow the conditions below if the cleaning is necessary after soldering.

Solvent	We recommend to use alcohols solvent such as, isopropyl alcohols
Temperature	Under 30℃ within 3 minutes
Ultrasonic Cleaning	15W／Below 1 liter (capacity of tank)
Drying	Under 100℃ within 3 minutes

Notes

1) The information contained herein is subject to change without notice.

2) Before you use our Products, please contact our sales representative and verify the latest specifications :

3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.

4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.

6) The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communication, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.

7) The Products specified in this document are not designed to be radiation tolerant.

8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.

9) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.

10) ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.

11) ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.

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